HOSTAFORM® SlideX® C0304 XAP®2
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POM copolymer Injection molding grade with tribological modification for demanding applications that require prevention of audible noise caused by stick-slip phenomenon. Excellent tribological performance with low friction and low wear under various conditions of sliding against plastics and metals. Reduced emission grade. Emissions according to VDA 275 < 5 mg/kg.

Chemical abbreviation according to ISO 1043-1: POM Molding compound ISO 29988-1: POM-K | M-GNRS2 | 5-2 | - | POM copolymer

Product information

Resin Identification	POM		ISO 1043
Part Marking Code	>POM<		ISO 11469

Rheological properties

Melt volume-flow rate	24	cm^3/10min	ISO 1133
Temperature	374	°F	
Load	4.76	lb	
Molding shrinkage, parallel	1.9	%	ISO 294-4, 2577
Molding shrinkage, normal	1.8	%	ISO 294-4, 2577

Typical mechanical properties

Tensile modulus	363000	psi	ISO 527-1/-2
Tensile stress at yield, 50mm/min	8100	psi	ISO 527-1/-2
Tensile strain at yield, 50mm/min	8	%	ISO 527-1/-2
Nominal strain at break	45	%	ISO 527-1/-2
Flexural modulus	341000	psi	ISO 178
Flexural strength	11200	psi	ISO 178
Charpy impact strength, 23°C	71.4	$ftlb/in^2$	ISO 179/1eU
Charpy impact strength, -30°C	69	$ftlb/in^2$	ISO 179/1eU
Charpy notched impact strength, 23°C	2.62	$ftlb/in^2$	ISO 179/1eA
Charpy notched impact strength, -30°C	2.62	$ftlb/in^2$	ISO 179/1eA
Hardness, Rockwell, M-scale	80		ISO 2039-2
Ball indentation hardness, H 358/30	19100	psi	ISO 2039-1

Thermal properties

Melting temperature, 10°C/min	331	°F	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	194	°F	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	0.78	E-4/°F	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal	0.778	E-4/°F	ISO 11359-1/-2

Physical/Other properties

Humidity absorption, 2mm	0.2	%	Sim. to ISO 62
Water absorption, 2mm	0.65	%	Sim. to ISO 62
Density	0.0505	lb/in^3	ISO 1183

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Injection

Drying Recommended	no	
Drying Temperature	212	°F
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	383	°F
Min. melt temperature	356	°F
Max. melt temperature	410	°F
Max. screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	212	°F
Min. mold temperature	176	°F
Max. mold temperature	248	°F
Hold pressure range	8700 - 17400	psi
Hold Pressure Time (h is the max. wall thickness of the part in mm)	$2h^2$-3	s
Back pressure	580	psi
Ejection temperature	271	°F

Automotive

OEM	STANDARD	ADDITIONAL INFORMATION
Mercedes-Benz	DBL5404	BQF

Characteristics

Processing	Injection Molding
Special characteristics	Low wear / Low friction, High Flow, Low emissions

Additional information

Injection molding

Processing

See Processing Guide and Involve Celanese FTS support to obtain best quality parts

Processing Notes

Pre-Drying

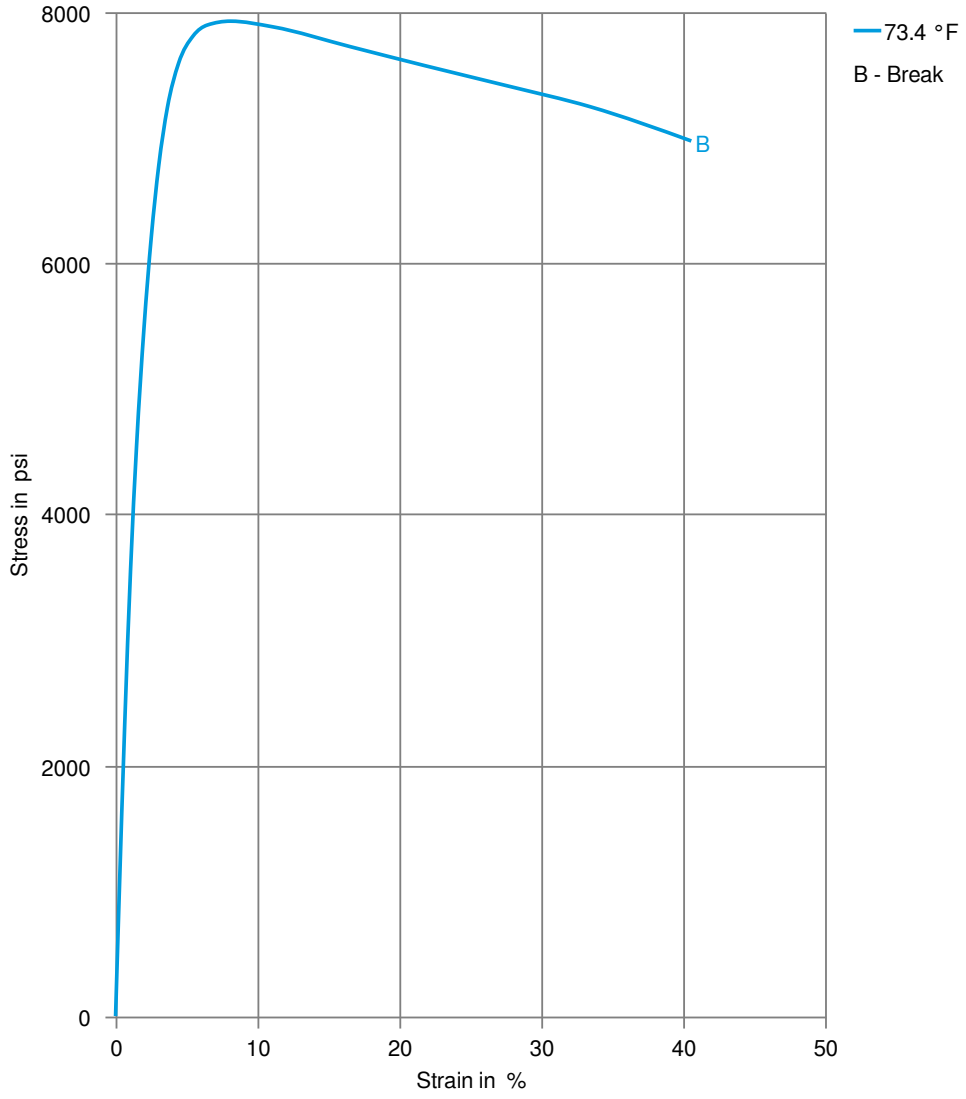
Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems

Storage

The product can then be stored in standard conditions until processed.

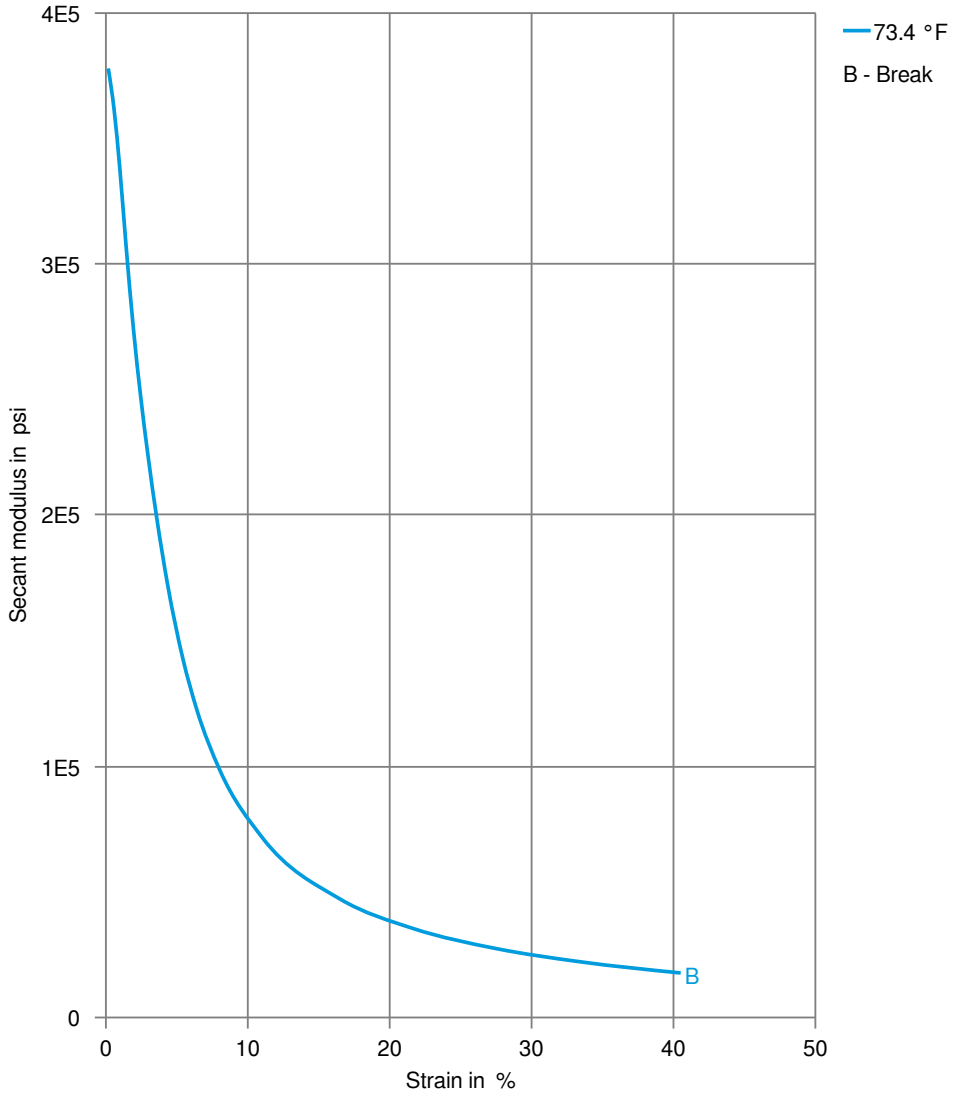
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Stress-strain



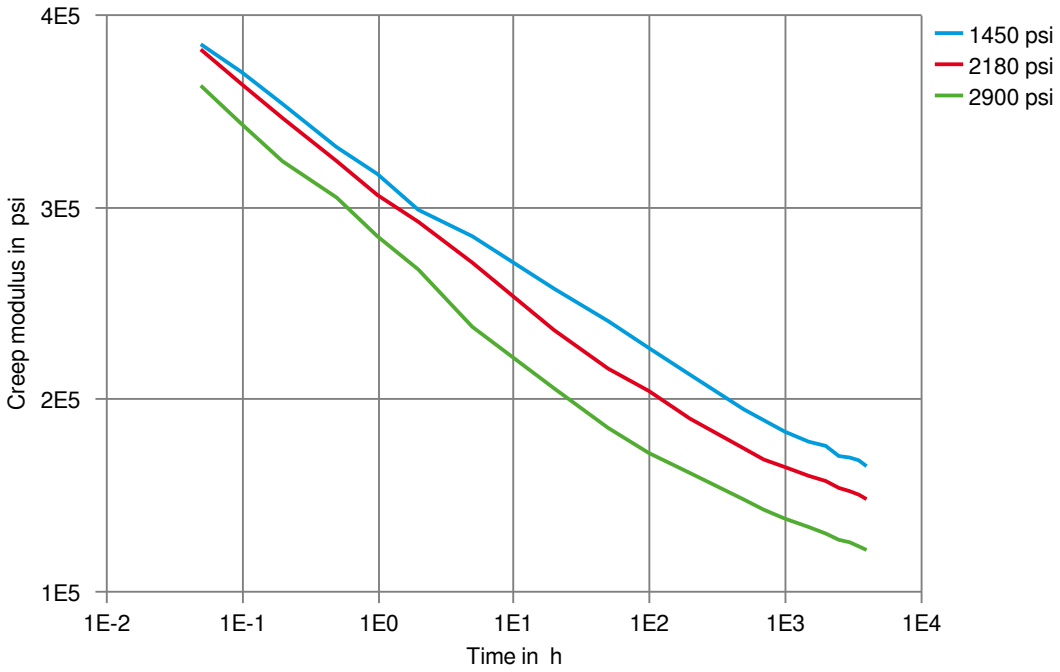
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Secant modulus-strain



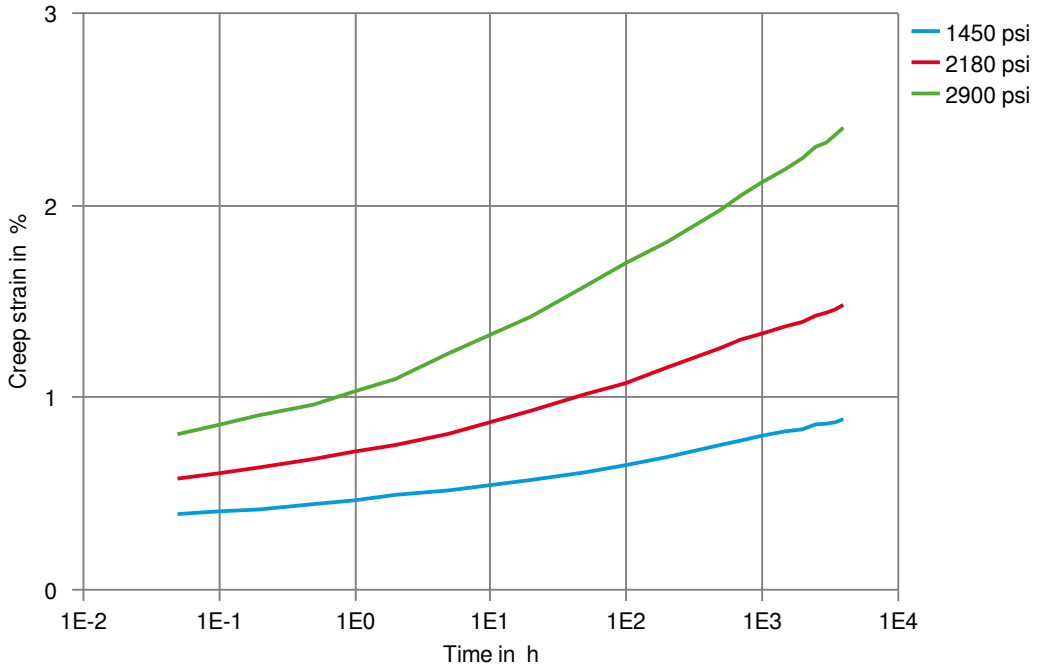
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Creep modulus-time 73.4 °F



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Creep strain-time 73.4 °F



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